

# **Film Capacitors**

Metallized Polypropylene Film Capacitors (MKP)

Series/Type: B32774 ... B32778

Date: May 2011

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## MKP DC link - high density series

## Typical applications

For compact design of:

- Frequency converters
- Industrial and high-end power supplies
- Solar inverters

#### Climatic

- Max. operating temperature: 105 °C (case)
- Climatic category (IEC 60068-1): 40/85/56

## Construction

- Dielectric: polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

#### **Features**

- Capacitance values up to 110 μF
- High CV product, compact
- Excellent self-healing properties
- Overvoltage capability
- Low losses with high current capability
- High reliability
- Long useful life

## Terminals

- Parallel wire leads, lead-free tinned
- 2-pin and 4-pin versions
- Standard lead lengths: 6 -1 mm
- Special lead lengths are available on request

## Marking

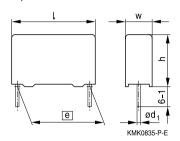
Manufacturer's logo, lot number, date code, rated capacitance (coded), capacitance tolerance (code letter), rated DC voltage

## **Delivery mode**

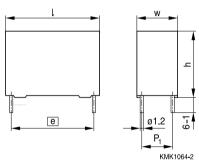
Bulk (untaped, lead length 6-1 mm)

## **Dimensional drawings**

2-pin version



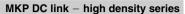
4-pin version



Dimensions in mm

Version	Lead spacing e ±0.4	Lead diameter d <sub>1</sub>	Туре
2-pin	27.5	0.8	B32774D
2-pin	37.5	1.0	B32776E
4-pin	37.5	1.2	B32776G
4-pin	52.5	1.2	B32778G







## Overview of available types

Lead spacing 27.5 mm			37.5 mm				52.5 mm					
Туре	B327	74			B327	B32776				78		
Page	4				5				7			
V <sub>R</sub> (V DC)	450	800	1100	1300	450	800	1100	1300	450	800	1100	1300
C <sub>R</sub> (μF)												
1.5												
2.0												
3.0												
5.0												
7.0												
8.0												
10												
12												
14												
15												
16												
20						was financial of						
22												
25												
27												
30												
35												
40												
45												
50												
55												
60												
75												
80												
100												
110												





## MKP DC link - high density series

## Ordering codes and packing units (lead spacing 27.5 mm)

C <sub>R</sub>	Max. dimensions	P <sub>1</sub>	Ordering code	I <sub>RMS,max</sub>	I <sub>RMS,max</sub>	ESR <sub>typ</sub>	Untaped
	$w \times h \times I$		(composition see	70 °C	70 °C	70 °C	
			below)	10 kHz	20 kHz	10 kHz	
μF	mm	mm		Α	Α	$m\Omega$	pcs./MOQ
$V_{R,70^{\circ}C}$	= 450 V DC, V <sub>op,85</sub> °(	= 4	50 V DC				
5.0	$11.0 \times 21.0 \times 31.5$	_	B32774D4505+000	5.0	4.5	8.5	2352
10	$15.0 \times 24.5 \times 31.5$	_	B32774D4106+000	6.5	6.0	7.5	1680
22	$22.0 \times 36.5 \times 31.5$	_	B32774D4226+000	10.0	9.0	5.0	784
V <sub>R,70</sub> °C	= 800 V DC, V <sub>op,85</sub> °c	c = 7	00 V DC				
3.0	$11.0 \times 21.0 \times 31.5$	_	B32774D8305+000	5.0	4.5	9.0	2352
5.0	$14.0 \times 24.5 \times 31.5$	_	B32774D8505+000	5.0	4.5	7.0	1848
12	$22.0\times36.5\times31.5$	_	B32774D8126+000	6.0	5.5	6.5	784
V <sub>R,70</sub> °C	= 1100 V DC, V <sub>op,85</sub> °c	= 9	20 V DC				
2.0	$12.5 \times 21.5 \times 31.5$	_	B32774D0205+000	4.0	3.5	11.0	2100
5.0	$19.0 \times 30.0 \times 31.5$	_	B32774D0505+000	6.5	6.0	7.0	896
7.0	$22.0\times36.5\times31.5$	_	B32774D0705+000	7.5	7.0	5.5	784
V <sub>R,70</sub> °C	V <sub>R,70</sub> ° <sub>C</sub> = 1300 V DC, V <sub>op,85</sub> ° <sub>C</sub> = 1100 V DC						
1.5	$12.5 \times 21.5 \times 31.5$	_	B32774D1155+000	4.5	4.0	10.5	2100
3.0	$18.0 \times 27.5 \times 31.5$	_	B32774D1305+000	6.0	5.5	7.0	1428
5.0	$22.0 \times 36.5 \times 31.5$	_	B32774D1505+000	8.0	7.0	6.0	784

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

## Composition of ordering code

+ = Capacitance tolerance code:

K = +10%





## MKP DC link - high density series

## Ordering codes and packing units (lead spacing 37.5 mm)

C <sub>R</sub>	Max. dimensions	$P_1$	Ordering code	I <sub>RMS,max</sub>	I <sub>RMS,max</sub>	ESR <sub>typ</sub>	Untaped
	$w \times h \times I$		(composition see	70 °C	70 °C	70 °C	
			below)	10 kHz	20 kHz	10 kHz	
μF	mm	mm	,	Α	Α	mΩ	pcs./MOQ
$V_{R,70^{\circ}C} = 450 \text{ V DC}, V_{op,85^{\circ}C} = 450 \text{ V DC}$			0 V DC				
30	$20.0 \times 39.5 \times 41.5$	10.2	B32776G4306+000	12.5	11.5	8.0	640
30	$20.0\times39.5\times41.5$	_	B32776E4306+000	11.5	10.5	9.0	640
35	$28.0\times37.0\times42.0$	10.2	B32776G4356+000	13.5	12.5	8.0	440
35	$28.0\times37.0\times42.0$	_	B32776E4356+000	12.5	11.5	9.0	440
40	$28.0\times37.0\times42.0$	10.2	B32776G4406+000	14.5	13.5	5.0	440
40	$28.0\times37.0\times42.0$	_	B32776E4406+000	13.5	12.5	5.5	440
50	$28.0\times42.5\times41.5$	10.2	B32776G4506+000	16.0	15.0	4.0	440
50	$28.0\times42.5\times41.5$	_	B32776E4506+000	15.0	14.0	4.0	440
60	$30.0\times45.0\times42.0$	_	B32776E4606+000	16.5	15.0	3.0	400
$V_{R,70^{\circ}C} = 800 \text{ V DC}, V_{op,85^{\circ}C} = 700 \text{ V DC}$							
14	$18.0 \times 32.5 \times 41.5$	_	B32776E8146+000	10.0	9.0	7.5	720
15	$20.0\times39.5\times41.5$	10.2	B32776G8156+000	10.5	9.5	7.0	640
20	$28.0\times37.0\times42.0$	10.2	B32776G8206+000	12.0	11.0	5.5	440
20	$28.0\times37.0\times42.0$	_	B32776E8206+000	11.5	10.5	6.5	440
22	$28.0\times37.0\times42.0$	10.2	B32776G8226+000	13.0	12.0	5.0	440
25	$28.0\times42.5\times41.5$	_	B32776E8256+000	13.5	12.5	4.5	440
30	$30.0\times45.0\times42.0$	20.3	B32776G8306+000	15.0	14.0	3.5	400
30	$30.0\times45.0\times42.0$	_	B32776E8306+000	14.0	13.0	5.0	400
V <sub>R,70</sub> ° <sub>C</sub>	= 1100 V DC, $V_{op,85}$ $^{\circ}$ C	= 92	0 V DC				
12	$20.0 \times 39.5 \times 41.5$	10.2	B32776G0126+000	11.0	10.0	6.5	640
12	$20.0\times39.5\times41.5$	_	B32776E0126+000	10.0	9.0	7.0	640
14	$28.0 \times 37.0 \times 42.0$	10.2	B32776G0146+000	13.0	12.0	5.5	440
14	$28.0 \times 37.0 \times 42.0$	_	B32776E0146+000	12.0	11.0	6.0	440
16	$28.0 \times 42.5 \times 41.5$	10.2	B32776G0166+000	13.0	12.0	5.0	440
16	$28.0 \times 42.5 \times 41.5$	_	B32776E0166+000	12.0	11.0	5.5	440
20	$30.0\times45.0\times42.0$	20.3	B32776G0206+000	15.0	13.0	3.0	400
20	$30.0\times45.0\times42.0$	_	B32776E0206+000	13.0	12.0	3.5	400

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

## Composition of ordering code

+ = Capacitance tolerance code:

 $K=\pm 10\%$ 





## MKP DC link - high density series

## Ordering codes and packing units (lead spacing 37.5 mm)

C <sub>R</sub>	Max. dimensions	P <sub>1</sub>	Ordering code	I <sub>RMS,max</sub>	I <sub>RMS,max</sub>	ESR <sub>typ</sub>	Untaped
	$w \times h \times I$		(composition see	70 °C	70 °C	70 °C	
			below)	10 kHz	20 kHz	10 kHz	
μF	mm	mm		Α	Α	mΩ	pcs./MOQ
V <sub>R,70</sub> ° <sub>C</sub>	V <sub>R,70</sub> ° <sub>C</sub> = 1300 V DC, V <sub>op,85</sub> ° <sub>C</sub> = 1100 V DC						
8.0	$20.0 \times 39.5 \times 41.5$	10.2	B32776G1805+000	9.0	8.0	8.0	640
10	$28.0 \times 37.0 \times 42.0$	10.2	B32776G1106+000	12.0	11.0	6.5	440
10	$28.0 \times 37.0 \times 42.0$	_	B32776E1106+000	11.0	10.0	7.0	440
12	$28.0 \times 42.5 \times 41.5$	10.2	B32776G1126+000	13.0	12.0	5.5	440
14	$30.0 \times 45.0 \times 42.0$	_	B32776E1146+000	13.0	12.0	5.0	400

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

## Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$ 



# MKP 52.5 **←**

## MKP DC link - high density series

## Ordering codes and packing units (lead spacing 52.5 mm)

C <sub>R</sub>	Max. dimensions	P <sub>1</sub>	Ordering code	I <sub>RMS,max</sub>	I <sub>RMS,max</sub>	$ESR_{typ}$	Untaped
	$w \times h \times l$		(composition see	70 °C	70 °C	70 °C	
			below)	10 kHz	20 kHz	10 kHz	
μF	mm	mm		Α	Α	mΩ	pcs./MOQ
V <sub>R,70</sub> ° <sub>C</sub>	= 450 V DC, V <sub>op,85</sub> ° <sub>C</sub>	= 45	0 V DC				
75	$30.0\times45.0\times57.5$	20.3	B32778G4756+000	16.0	15.5	5.5	280
80	$30.0\times45.0\times57.5$	20.3	B32778G4806+000	16.5	16.0	5.0	280
100	$35.0 \times 50.0 \times 57.5$	20.3	B32778G4107+000	18.0	18.0	4.0	108
110	$35.0\times50.0\times57.5$	20.3	B32778G4117+000	19.0	19.0	4.0	108
V <sub>R,70</sub> ° <sub>C</sub>	= 800 V DC, V <sub>op,85</sub> ° <sub>0</sub>	= 70	0 V DC				
45	$30.0 \times 45.0 \times 57.5$	20.3	B32778G8456+000	16.0	15.0	4.0	280
55	$35.0\times50.0\times57.5$	20.3	B32778G8556+000	17.0	16.0	3.5	108
60	$35.0\times50.0\times57.5$	20.3	B32778G8606+000	19.0	18.0	3.0	108
V <sub>R,70</sub> ° <sub>C</sub>	= 1100 V DC, V <sub>op,85</sub> ° <sub>C</sub>	= 92	0 V DC				
30	$30.0\times45.0\times57.5$	20.3	B32778G0306+000	16.0	14.0	5.0	280
40	$35.0\times50.0\times57.5$	20.3	B32778G0406+000	20.0	20.0	3.5	108
V <sub>R,70</sub> °C	V <sub>R,70</sub> °C = 1300 V DC, V <sub>op,85</sub> °C = 1100 V DC						
20	$30.0 \times 45.0 \times 57.5$	20.3	B32778G1206+000	14.0	13.0	5.5	280
25	$35.0 \times 50.0 \times 57.5$	20.3	B32778G1256+000	17.0	16.0	4.5	108
27	$35.0\times50.0\times57.5$	20.3	B32778G1276+000	17.5	16.0	4.5	108

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further E series and intermediate capacitance values on request.

## Composition of ordering code

+ = Capacitance tolerance code:

K = +10%





## MKP DC link - high density series

## Technical data

Reference standard: IEC 61071. All data given at T = 20  $^{\circ}$ C, unless otherwise specified.

Operating temperate	ure range (case)	Max. op	erating ten	nperature, T <sub>op,</sub>	<sub>max</sub> +105 °C
		Upper o	ategory ter	nperature T <sub>max</sub>	, +85 °C
		Lower o	ategory ter	mperature T <sub>min</sub>	-40 °C
ESR (at 10 kHz)	LS 27.5	< 3.0 ⋅			
	LS 37.5	< 2.5 ·	$ESR_{typ}$		
	LS 52.5	< 2.0 ·	$ESR_{typ}$		
Insulation Resistance	Insulation Resistance R <sub>ins</sub>				
given as time consta					
$\tau = C_R \cdot R_{ins}$ , rel. hur	midity ≤ 65%				
(minimum as-delive	red values)				
DC test voltage bety	veen terminals (10 s)	1.5 · V <sub>F</sub>	3		
DC test voltage term	ninal to case (10 s)	2110 V	AC, 50 Hz		
Maximum peak curr	ent (A)	I <sub>P,max</sub> =	$C_R - \frac{dV}{dt}$		
Damp heat test		56 days	s/40 °C/93%	6 relative hum	idity
Limit values after da	imp heat test	Capacit	ance chan	ge I ∆C/C I	≤ 5%
		Dissipa	tion factor o	change ∆ tan 8	$5 \le 1.5 \cdot 10^{-3} \text{ (at 1 kHz)}$
		Insulation	on resistan	ce R <sub>ins</sub>	$\geq$ 50% of minimum
					as-delivered values
Reliability:	Failure rate $\lambda$	50 fit (≤	1 · 10 <sup>-9</sup> /h)	at 0.5 · V <sub>R</sub> , 40	) °C
	Service life t <sub>SL</sub>	100 000	h at V <sub>R</sub> an	ıd 70 °C	
		For con	version to	other operating	g conditions, refer to
		chapter	"Quality, 2	Reliability".	
V <sub>R</sub> (V DC)		450	800	1100	1300
Continuous operation	n voltage				
V <sub>op</sub> (V DC) at 70 °C		450	800	1100	1300
Continuous operation	n voltage				
V <sub>op</sub> (V DC) at 85 °C		450	700	920	1100
For temperatures be	1%/°C of derating respect V <sub>op</sub> at 70 °C				
70 °C and 85 °C		(no dera	ating at 450	V DC series)	



## MKP DC link - high density series



## Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in  $V/\mu s$ .

## Note:

The values of dV/dt provided below must not be exceeded in order to avoid damaging the capacitor.

## dV/dt values

Lead spacing	27.5 r	27.5 mm			37.5 r	37.5 mm				nm		
Туре	B327	74			B327	B32776			B32778			
V <sub>R</sub> (V DC)	450	800	1100	1300	450	800	1100	1300	450	800	1100	1300
C <sub>R</sub> (µF)	dV/dt	in V/μ	3		•	•		•			•	
1.5	_	_	_	100	_	_	_	_	_	_	_	_
2.0	_	-	75	_	-	-	-	-	_	_	-	_
3.0	_	40	_	100	_	_	_	_	_	_	_	_
5.0	30	40	75	100	_	_	_	_	_	_	_	_
7.0	_	_	75	_	_	_	_	_	_	_	_	_
8.0	_	_	_	_			_	73	_	_	_	_
10	30	-	-	_	-	-	-	73	_	_	-	_
12	_	40	_	_	_	_	54	73	_	_	_	_
14	_	_	_	_	_	22	54	73	_	_	_	_
15	_	-	-	_	-	22	-	-	_	_	-	_
16	_	_	_	_	_	_	54	_	_	_	_	_
20	_	_	_	_	_	22	54	_	_	_	_	50
22	30	_	_	_	_	22	_	_	_	_	_	_
25	_	_	_	_	_	22	_	_	_	_	_	50
27	_	-	_	_	_	_	-	_	_	_	_	50
30	_	_	_	_	21	22	_	_	_	_	35	-
35	_	_	_	_	21	_	_	_	_	_	_	_
40	-	_	_	_	21	_	_	_	_	_	35	_
45	_	-	-	_	-	-	-	-	_	15	-	_
50	_	-	-	_	21	-	-	-	_	_	-	_
55	_	_	_	_	_	_	_	_	_	15	_	_
60	_	_	_	_	21	_	_	_	_	15	_	_
75	_	_	_	_	_	_	_	_	14	_	_	_
80	_	_	_	_	_	_	_	_	14	_	_	_
100	-	ı	-	_	-	-	-	-	14	_	-	_
110	_	_	_	_	_	_	_	_	14	_	_	_



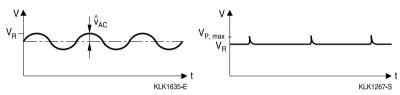


## MKP DC link - high density series

#### **ESL** values

		ESL
2-pin	B32774D	25 nH
	B32776E	10 nH
4-pin	B32776G	15 nH
	B32778G	15 nH

## **Typical waveforms**



## Restrictions:

 $V_R$ : Maximum operating peak voltage of either polarity but of a non-reversing waveform, for which the capacitor has been designed for continuous operation.

 $\hat{v}_{AC} \leq 0.2 \cdot V_{R}$ 

**V**<sub>P.max</sub>: Maximum permissible recurrent voltage that may appear for 2% of the period.



## MKP DC link - high density series



## Mounting guidelines

## 1 Soldering

## 1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

## 1.2 Resistance to soldering heat

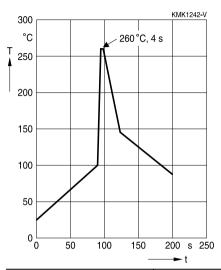
Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Series	S	Solder bath temperature	Soldering time
MKT	boxed (except 2.5 $\times$ 6.5 $\times$ 7.2 mm)	260 ±5 °C	10 ±1 s
	coated		
	uncoated (lead spacing > 10 mm)		
MFP			
MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5 ±1 s
MKP	(lead spacing ≤ 7.5 mm)		< 4 s
MKT	uncoated (lead spacing ≤ 10 mm)		recommended soldering
	insulated (B32559)		profile for MKT uncoated
			(lead spacing ≤ 10 mm) and
			insulated (B32559)





## MKP DC link - high density series



Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 $\pm 0.5)$ mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
$tan  \delta$	As specified in sectional specification



## MKP DC link - high density series



#### 1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature  $T_{\text{max}}$ . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
  - MKP/MFP 110 °C
  - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

#### **Uncoated capacitors**

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering





## MKP DC link - high density series

## 2 Cleaning

To determine whether the following solvents, often used to remove flux residues and other substances, are suitable for the capacitors described, refer to the table below:

Туре	Ethanol, isopropanol, n-propanol	n-propanol-water mixtures, water with surface tension-reducing tensides (neutral)	Solvent from table A (see next page)	Solvent from table B (see next page)
MKT (uncoated)	Suitable	Unsuitable	In part suitable	Unsuitable
MKT, MKP, MFP (coated/boxed)		Suitable	Suitable	

Even when suitable solvents are used, a reversible change of the electrical characteristics may occur in uncoated capacitors immediately after they are washed. Thus it is always recommended to dry the components (e.g. 4 h at 70 °C) before they are subjected to subsequent electrical testing.

**Table A**Manufacturers' designations for trifluoro-trichloro-ethane-based cleaning solvents (selection)

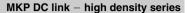
Trifluoro-trichloro-	Mixtures of trifluoro-trichloro-ethane with ethanol and	Manufacturer
ethane	isopropanol	
Freon TF	Freon TE 35; Freon TP 35; Freon TES	Du Pont
Frigen 113 TR	Frigen 113 TR-E; Frigen 113 TR-P; Frigen TR-E 35	Hoechst
Arklone P	Arklone A; Arklone L; Arklone K	ICI
Kaltron 113 MDR	Kaltron 113 MDA; Kaltron 113 MDI; Kaltron 113 MDI 35	Kali-Chemie
Flugene 113	Flugene 113 E; Flugene 113 IPA	Rhone-Progil

## Table B (worldwide banned substances)

Manufacturers' designations for unsuitable cleaning solvents (selection)

Mixtures of chlorinated hydrocarbons and ketones with fluorated hydrocarbons	Manufacturer
Freon TMC; Freon TA; Freon TC	Du Pont
Arklone E	ICI
Kaltron 113 MDD; Kaltron 113 MDK	Kali-Chemie
Flugene 113 CM	Rhone-Progil







## 3 Embedding of capacitors in finished assemblies

In many applications, finished circuit assemblies are embedded in plastic resins. In this case, both chemical and thermal influences of the embedding ("potting") and curing processes must be taken into account.

Our experience has shown that the following potting materials can be recommended: non-flexible epoxy resins with acid-anhydride hardeners; chemically inert, non-conducting fillers; maximum curing temperature of 100  $^{\circ}$ C.

#### Caution:

Consult us first if you wish to embed uncoated types!





## MKP DC link - high density series

## Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"





# MKP DC link - high density series

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"





## MKP DC link - high density series

## Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
$\alpha_{\text{C}}$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
Α	Capacitor surface area	Kondensatoroberfläche
$eta_{ extsf{C}}$	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
$C_{R}$	Rated capacitance	Nennkapazität
$\Delta C$	Absolute capacitance change	Absolute Kapazitätsänderung
ΔC/C	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔΤ	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
$\Delta V$	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f <sub>1</sub>	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
$f_2$	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f <sub>r</sub>	Resonant frequency	Resonanzfrequenz
F <sub>D</sub>	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
$F_T$	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I <sub>C</sub>	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)





## MKP DC link - high density series

Symbol	English	German
I <sub>RMS</sub>	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
İz	Capacitance drift	Inkonstanz der Kapazität
$k_0$	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
$\lambda_0$	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
$\lambda_{\text{test}}$	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
$P_{diss}$	Dissipated power	Abgegebene Verlustleistung
$P_{gen}$	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
$R_{i}$	Internal resistance	Innenwiderstand
$R_{\text{ins}}$	Insulation resistance	Isolationswiderstand
$R_P$	Parallel resistance	Parallelwiderstand
$R_s$	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan $\delta$	Dissipation factor	Verlustfaktor
$tan \; \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
$tan \; \delta_{\scriptscriptstyle P}$	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
$tan \; \delta_{\text{S}}$	Series component of dissipation factor	Serienanteil des Verlustfaktors
T <sub>A</sub>	Ambient temperature	Umgebungstemperatur
$T_{max}$	Upper category temperature	Obere Kategorietemperatur
$T_{min}$	Lower category temperature	Untere Kategorietemperatur
t <sub>OL</sub>	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
02	and voltage	-spannung
$T_{op}$	Operating temperature	Beriebstemperatur
T <sub>R</sub>	Rated temperature	Nenntemperatur
$T_{ref}$	Reference temperature	Referenztemperatur
t <sub>SL</sub>	Reference service life	Referenz-Lebensdauer
V <sub>AC</sub>	AC voltage	Wechselspannung





## MKP DC link - high density series

Symbol	English	German
V <sub>C</sub>	Category voltage	Kategoriespannung
$V_{\text{C,RMS}}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
$V_{CD}$	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
$V_{ch}$	Charging voltage	Ladespannung
$V_{DC}$	DC voltage	Gleichspannung
$V_{FB}$	Fly-back capacitor voltage	Spannung (Flyback)
$V_{i}$	Input voltage	Eingangsspannung
$V_{o}$	Output voltage	Ausgangssspannung
$V_{op}$	Operating voltage	Betriebsspannung
$V_p$	Peak pulse voltage	Impuls-Spitzenspannung
$V_{pp}$	Peak-to-peak voltage Impedance	Spannungshub
$V_{R}$	Rated voltage	Nennspannung
ν̂ <sub>R</sub>	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
$V_{\text{RMS}}$	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
$V_{SC}$	root-mean-square value S-correction voltage	Spannung bei Anwendung "S-correction"
V <sub>SC</sub>	Snubber capacitor voltage	Spannung bei Anwendung
V <sub>Sn</sub>	Shubber capacitor voltage	"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



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